

L I M I T E D T E N D E R
N O T I C E

Tender Ref. No.	Date	Tender Due Date
PUR-14/24/2020-MCAD_DIV_SAM_CHENNAI-9483	18-06-2020	06-07-2020

To

Dear Sir,

The Purchase Officer, SAMEER-Centre for Electromagnetics invites sealed tender for the supply of materials as per details given below:

SI.No	Description of Items	Qty No's
1	14 Layer PCB fabrication on highfrequency laminate (Specification List Attached)	3

Terms and Conditions

1. Price quoted should be on the basis of Destination delivery at Perungudi Campus, Chennai 600 096.
2. Delivery / Completion period should be clearly indicated.
3. Excise Duty, GST Percentage should be clearly indicated if admissible. Not eligible for FORM 'C' / 'D'
4. WE ARE EXEMPTED FROM EXCISE DUTY
5. Quotation should be valid for atleast 60 days from the date of opening of the tender
6. Quotation should be sent in sealed envelope super scribing the tender reference number and tender due date.
YOUR OFFER WILL NOT BE CONSIDERED IF OUR TENDER REFERENCE NO. &
TENDER DUE DATE IS NOT MENTIONED ON COVER.
7. Late tenders will not be accepted under any circumstances
8. We reserve the right to accept or reject any quotations fully or partly without assigning any reasons.
9. For Further Clarification Please Contact 044-22544061 / 22544020 Email: purchase.chn.sameer@nic.in
10. Unsolicited bids shall not be considered

P. Ramamoorthi
(P.Ramamoorthi)
Head - Administration
Contd..

S.No	REQUIREMENTS	VALUE
1	Board Thickness	3.5 mm(Approximate)
2	Via Requirements	
	a.Through hole	Yes
	b.Blind via	Layer 1 to Layer 2,Layer 1 to Layer 4, Layer 1 to layer 8
	c.Buried via	Nil
3	Via hole size	
	a.minimum hole size-mechanical	0.25mm
	b.maximum hole size-mechanical	4mm
	c.Approximate no of holes	700(maximum)
4	No. of Copper layers	14
5	Substrate Material(Top)	Rogers RO4350B,10 mils
6	Prepreg material	FR4
7	Substrate Material(Bottom)	Rogers RO4350B,10 mils
6	Board Size	65 mm x 75mm
7	Minimum Track With	0.2mm
8	Minimum gap	0.15mm
9	Board overall thickness tolerance	< +/- 10%
10	Solder mask	Top and bottom layer
11	Surface finish	ENIG / ENEPIG
12	Copper thickness	35 microns(layer1 & 14) 18microns (inner layers)
13	Solder mask color	no preference
14	Silk screen color	Top,White
15	ROHS compliance	required
16	Via on pad	Yes
17	Via filling	No
18	Edge plating	No
19	PCB type	IPC CLASS 2, Industrial
20	Fabrication file format	Gerber files RS-274X format
21	Impedance Control	Not required
22	Electrical testing	required
23	No of boards required	5 numbers
24	Fabrication lead time	10 working days

